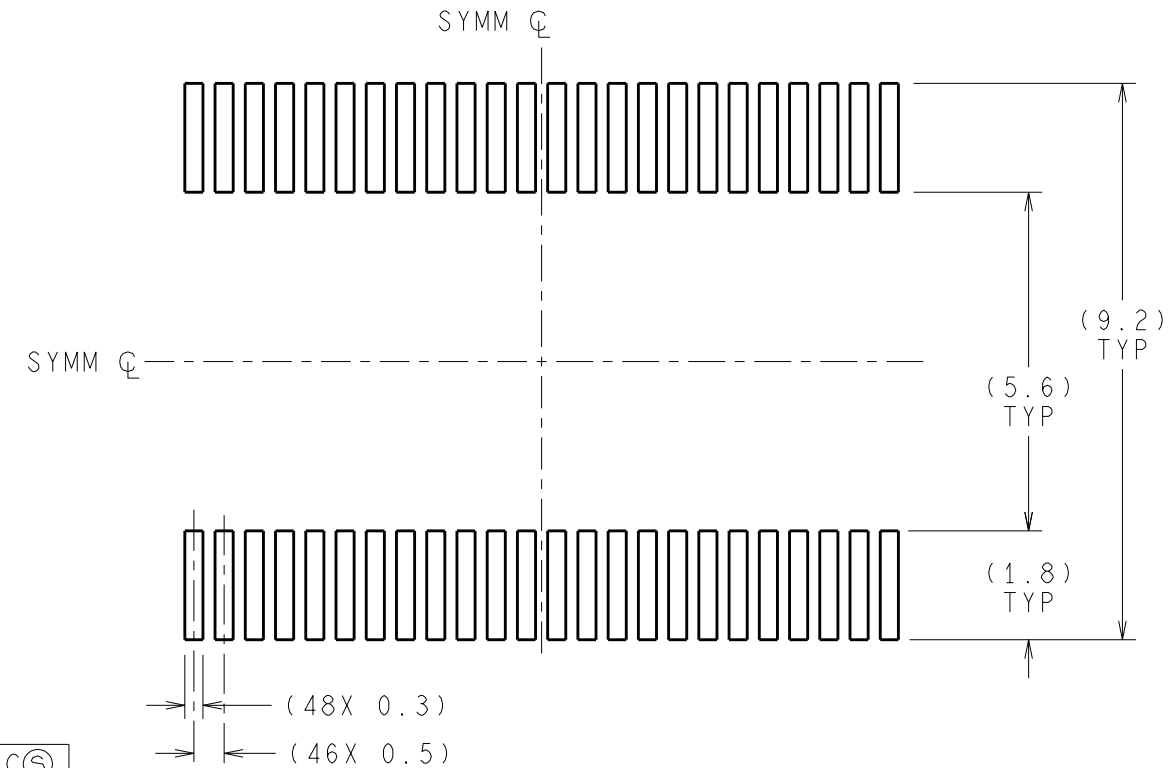
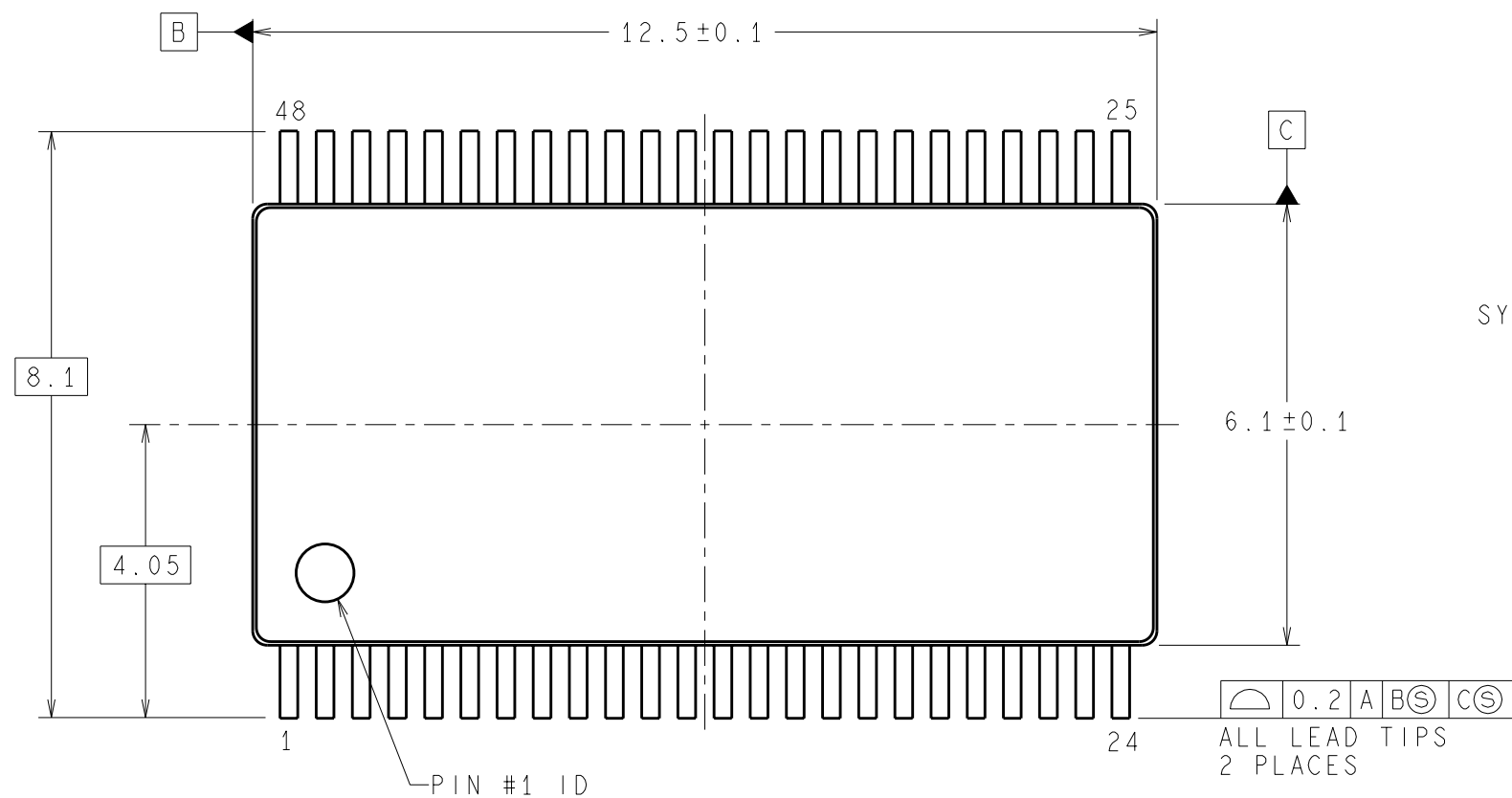
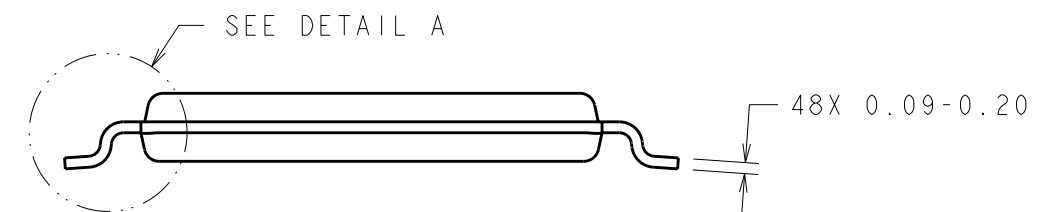
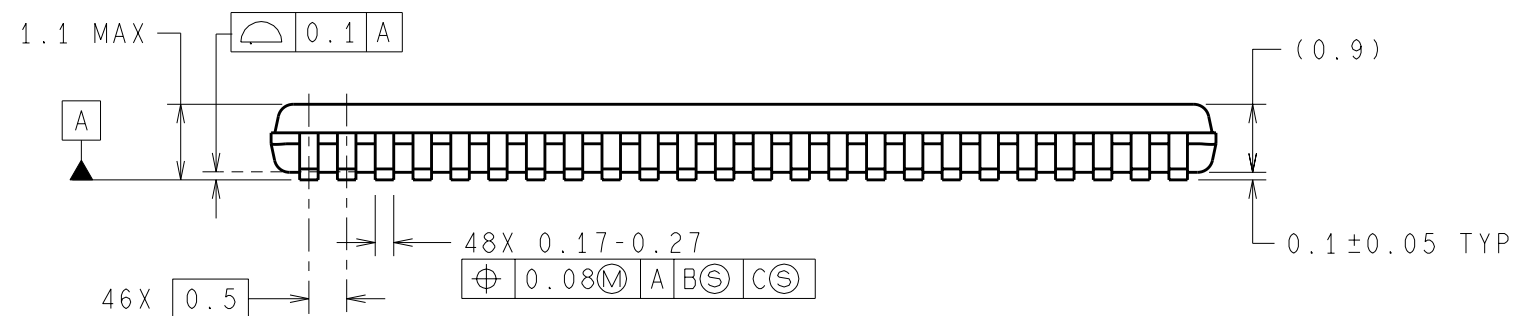


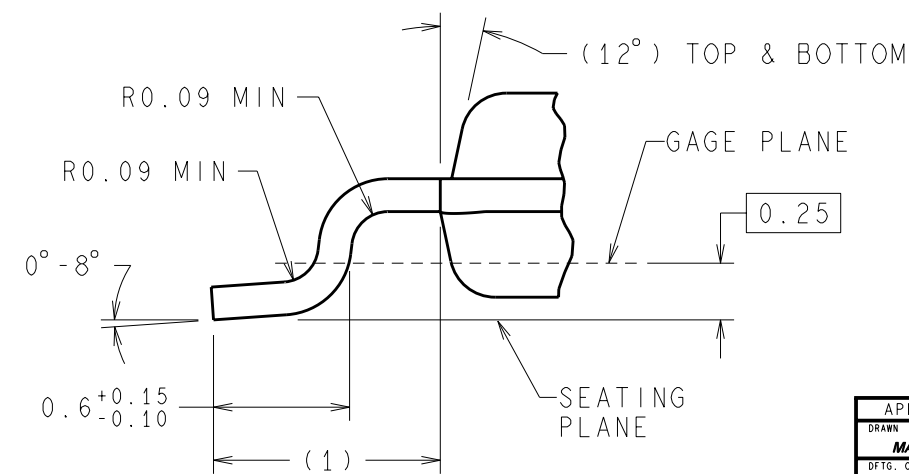
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
B	REDRAW ON PROJE; ADD LAND PATTERN RECOMENDATION	11322	02/16/1996	MS/CS
C	DIM 6.1±0.1 WAS 6.1±0.01; REVISE NOTE 1.	197	12/06/2000	MS/CD
D	LEAD POS.TOL WAS 0.13; CHANGE DWG FORMAT TO "B" SIZE.	729	07/31/2002	MS/RW
E	ADD LEAD FINISH NOTE & UPDATE TITLE.	976	04/02/2003	MS/RW



LAND PATTERN RECOMENDATION



DIMENSIONS ARE IN MILLIMETERS



DETAIL A TYPICAL

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
- REFERENCE JEDEC REGISTRATION MO-153, VARIATION ED.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN <b>MARTA SUCHY</b>		02/16/1996	
DFTG. CHK. <b>THANH LEQUANG</b>		04/02/2003	
ENGR. CHK. <b>RANDALL WALBERG</b>		04/02/2003	
<b>MOLDED TSSOP, JEDEC, 12.5x6.1x0.9mm BODY, 48 LD, 0.50mm PITCH</b>			
PROJECTION 	SCALE <b>NTS</b>	SIZE <b>B</b>	DRAWING NUMBER <b>(SC)MKT-MTD48</b>
FORMERLY: N/A		REV <b>E</b>	
			SHEET 1 of 1